

MEMS Integrated Design for Inertial Sensors (MIDIS)



The MEMS Integrated Design for Inertial Sensors (MIDIS™) platform is designed to provide a standard process for manufacturing accelerometers and gyroscopes and integrating them into an Inertial Measurement Unit (IMU) for application areas such as consumer (mobile), automotive, aerospace and sports/health markets.

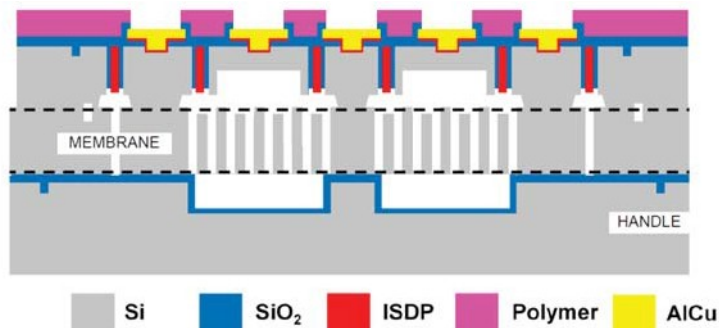
The MIDIS™ Platform is being offered as Multi-Project-Wafer (MPW) service through CMC Microsystems and is available for both academic and industrial R&D. Together CMC and Teledyne DALSA offer a seamless path from MPW design confirmation to volume manufacturing.

Features

- Getter-free, high-vacuum sealing allows resonator Q factors > 20,000
- Efficient wafer level packaging minimizes overall die size
- 1.5µm feature size in a 30µm thick membrane
- Comb height control allows out-of-plane sensing
- TSV allows compact design ready for co-packaging
- Deliver 40 copies for each design

Price

Fixed size 4mm x 4mm: \$9,830
Fixed size 4mm x 8mm: \$18,700
Fixed size 8mm x 8mm: \$37,300



Applications

- Accelerometers
- Gyroscopes
- Resonators
- Inertial sensor combos (Sensor fusion)

Additional Services Available

- CAD tool access
- Design kits
- Design consultation
- Access to CMC support engineers
- Design rule checking services
- Documentation including design handbooks, application notes and design methodologies
- Packaging & assembly services

Contact

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